

### Description

The new 0805L series device provides surface mount overcurrent protection for applications where space is at a premium and resettable protection is desired.

### Features

- RoHS compliant and lead-free
- Fast response to fault currents
- Compact design saves board space
- Low resistance
- Low-profile
- Compatible with high temperature solders

### Applications

- USB peripherals
- Disk drives
- CD-ROMs
- Plug and play protection for motherboards and peripherals
- Mobile phones - battery and port protection
- Disk drives
- PDAs / digital cameras
- Game console port protection

### Agency Approvals

| AGENCY | AGENCY FILE NUMBER |
|--------|--------------------|
|        | E183209            |
|        | R50082521          |

### Electrical Characteristics

| Part Number | Marking | I <sub>hold</sub> (A) | I <sub>trip</sub> (A) | V <sub>max</sub> (Vdc) | I <sub>max</sub> (A) | P <sub>d max.</sub> (W) | Maximum Time To Trip |             | Resistance           |                      |                       | Agency Approvals |   |
|-------------|---------|-----------------------|-----------------------|------------------------|----------------------|-------------------------|----------------------|-------------|----------------------|----------------------|-----------------------|------------------|---|
|             |         |                       |                       |                        |                      |                         | Current (A)          | Time (Sec.) | R <sub>min</sub> (Ω) | R <sub>typ</sub> (Ω) | R <sub>1max</sub> (Ω) |                  |   |
| 0805L010    | A       | 0.10                  | 0.30                  | 15                     | 100                  | 0.5                     | 0.50                 | 1.50        | 1.000                | 3.500                | 6.000                 | X                | X |
| 0805L020    | C       | 0.20                  | 0.50                  | 9                      | 100                  | 0.5                     | 8.00                 | 0.02        | 0.650                | 2.000                | 3.500                 | X                | X |
| 0805L035    | E       | 0.35                  | 0.75                  | 6                      | 100                  | 0.5                     | 8.00                 | 0.10        | 0.250                | 0.750                | 1.200                 | X                | X |
| 0805L050    | F       | 0.50                  | 1.00                  | 6                      | 100                  | 0.5                     | 8.00                 | 0.10        | 0.150                | 0.500                | 0.850                 | X                | X |
| 0805L075    | G       | 0.75                  | 1.50                  | 6                      | 40                   | 0.6                     | 8.00                 | 0.20        | 0.090                | –                    | 0.350                 | X                | X |
| 0805L100    | N       | 1.0                   | 1.95                  | 6                      | 40                   | 0.6                     | 8.00                 | 0.30        | 0.060                | –                    | 0.210                 | X                | X |

I<sub>hold</sub> = Hold current: maximum current device will pass without tripping in 20°C still air.

I<sub>trip</sub> = Trip current: minimum current at which the device will trip in 20°C still air.

V<sub>max</sub> = Maximum voltage device can withstand without damage at rated current (I<sub>max</sub>)

I<sub>max</sub> = Maximum fault current device can withstand without damage at rated voltage (V<sub>max</sub>)

P<sub>d</sub> = Power dissipated from device when in the tripped state at 20°C still air.

R<sub>min</sub> = Minimum resistance of device in initial (un-soldered) state.

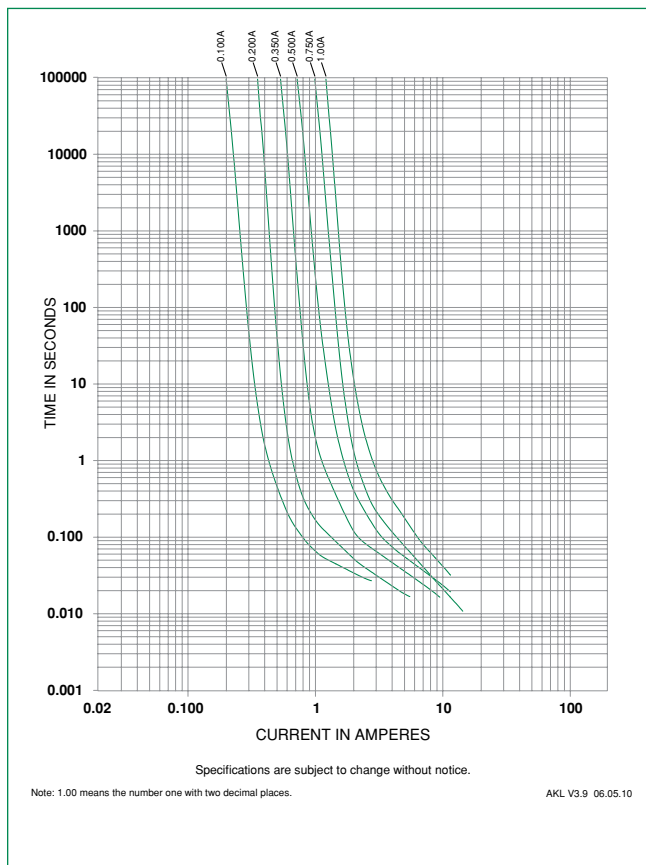
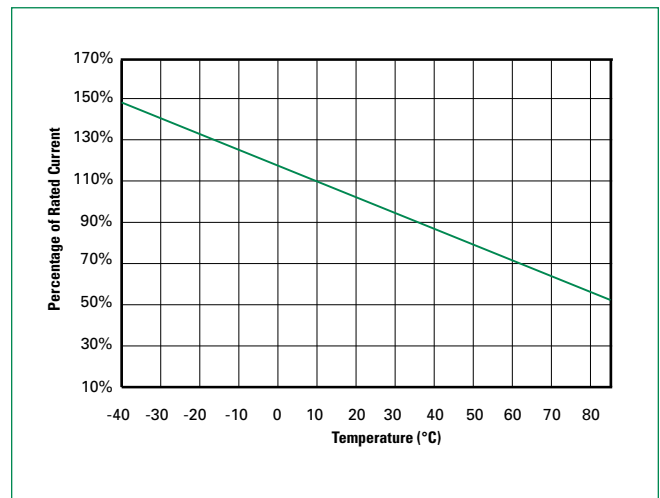
R<sub>typ</sub> = Typical resistance of device in initial (un-soldered) state.

R<sub>1max</sub> = Maximum resistance of device at 20°C measured one hour after tripping or reflow soldering of 260°C for 20 sec.

**Caution:** Operation beyond the specified rating may result in damage and possible arcing and flame.

**Temperature Derating**

| Part Number | Ambient Operation Temperature |       |      |      |      |      |      |      |      |
|-------------|-------------------------------|-------|------|------|------|------|------|------|------|
|             | -40°C                         | -20°C | 0°C  | 23°C | 40°C | 50°C | 60°C | 70°C | 85°C |
|             | Hold Current (A)              |       |      |      |      |      |      |      |      |
| 0805L010    | 0.14                          | 0.12  | 0.11 | 0.10 | 0.08 | 0.07 | 0.06 | 0.05 | 0.03 |
| 0805L020    | 0.28                          | 0.25  | 0.23 | 0.20 | 0.17 | 0.14 | 0.12 | 0.10 | 0.07 |
| 0805L035    | 0.47                          | 0.44  | 0.39 | 0.35 | 0.30 | 0.27 | 0.24 | 0.20 | 0.14 |
| 0805L050    | 0.68                          | 0.62  | 0.55 | 0.50 | 0.40 | 0.37 | 0.33 | 0.29 | 0.23 |
| 0805L075    | 1.00                          | 0.90  | 0.79 | 0.75 | 0.63 | 0.57 | 0.53 | 0.41 | 0.34 |
| 0805L100    | 1.35                          | 1.25  | 1.10 | 1.00 | 0.82 | 0.74 | 0.65 | 0.55 | 0.42 |

**Average Time Current Curves**

**Temperature Derating Curve**


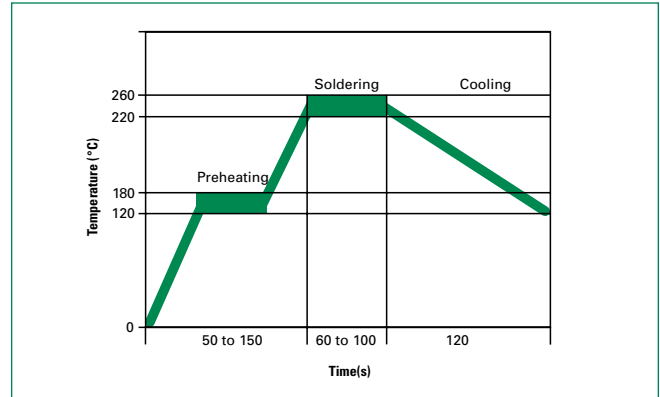
The average time current curves and temperature derating curve performance is affected by a number of variables, and these curves provided as guidance only. Customer must verify the performance in their application.

**Soldering Parameters**

|                                |                  |
|--------------------------------|------------------|
| Condition                      | Reflow           |
| Peak Temp/ Duration Time       | 260°C / 10 Sec   |
| Time above liquids (TAL) 220°C | 60 Sec ~ 100 Sec |
| Preheat 120°C~ 180°C           | 50 Sec ~ 150 Sec |
| Storage Condition              | 0°C~35°C, ≤70%RH |

- Recommended reflow methods: IR, vapor phase oven, hot air oven, N<sub>2</sub> environment for lead-free
- Devices are not designed to be wave soldered to the bottom side of the board.
- Recommended maximum paste thickness is 0.25mm (0.010 inch)
- Devices can be cleaned using standard industry methods and solvents.

**Note:** If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.


**Physical Specifications**

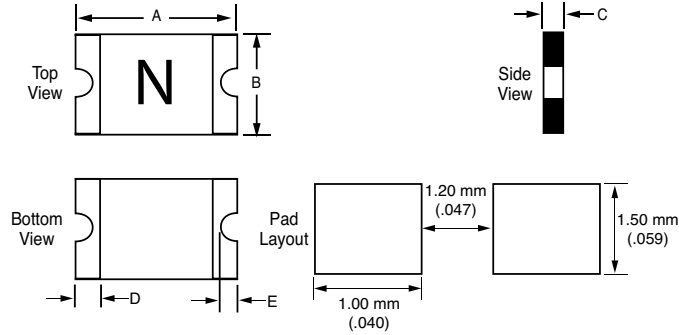
|                           |  |
|---------------------------|--|
| <b>Terminal Material</b>  | Gold-Plated Copper or Solder-Plated Copper (Solder Material: Matte Tin (Sn)) |
| <b>Lead Solderability</b> | Meets EIA Specification RS186-9E, ANSI/J-STD-002 Category 3.                 |

**Environmental Specifications**

|  |   |
|--|---|
| <b>Operating/Storage Temperature</b>                       | -40°C to +85°C  |
| <b>Maximum Device Surface Temperature in Tripped State</b> | 125°C   |
| <b>Passive Aging</b>                                       | +85°C, 1000 hours<br>±5% typical resistance change                                |
| <b>Humidity Aging</b>                                      | +85°C, 85%R.H. 1000 hours<br>±5% typical resistance change                        |
| <b>Thermal Shock</b>                                       | MIL-STD-202 Method 107G<br>+85°C/-40°C 20 times<br>-30% typical resistance change |
| <b>Solvent Resistance</b>                                  | MIL-STD-202, Method 215<br>No change  |
| <b>Vibration</b>   | MIL-STD-883C, Method 2007.1, Condition A<br>No change                             |

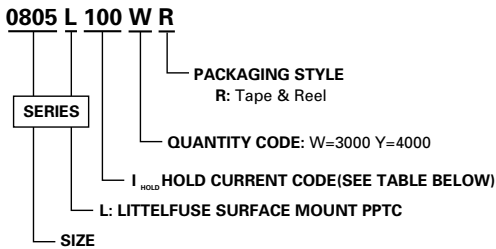
### Dimensions

MARKING CODE VARIES WITH AMPERAGE RATING (SEE CHART)  
SHOWN IS 1.0AMP RATING



| Part Number | A      |      |      |      | B      |      |      |      | C      |      |      |      | D      |      | E      |      |        |      |
|-------------|--------|------|------|------|--------|------|------|------|--------|------|------|------|--------|------|--------|------|--------|------|
|             | Inches |      | mm   |      | Inches |      | mm   |      | Inches |      | mm   |      | Inches | mm   | Inches | mm   | Inches | mm   |
|             | Min.   | Max. | Min. | Max. | Min.   | Max. | Min. | Max. | Min.   | Max. | Min. | Max. | Min.   | Min. | Min.   | Max. | Min.   | Max. |
| 0805L010    | 0.08   | 0.09 | 2.00 | 2.20 | 0.05   | 0.06 | 1.20 | 1.50 | 0.02   | 0.04 | 0.55 | 1.00 | 0.01   | 0.20 | 0.004  | 0.02 | 0.10   | 0.45 |
| 0805L020    | 0.08   | 0.09 | 2.00 | 2.20 | 0.05   | 0.06 | 1.20 | 1.50 | 0.02   | 0.04 | 0.55 | 1.00 | 0.01   | 0.20 | 0.004  | 0.02 | 0.10   | 0.45 |
| 0805L035    | 0.08   | 0.09 | 2.00 | 2.20 | 0.05   | 0.06 | 1.20 | 1.50 | 0.02   | 0.03 | 0.45 | 0.75 | 0.01   | 0.20 | 0.004  | 0.02 | 0.10   | 0.45 |
| 0805L050    | 0.08   | 0.09 | 2.00 | 2.20 | 0.05   | 0.06 | 1.20 | 1.50 | 0.03   | 0.05 | 0.75 | 1.25 | 0.01   | 0.20 | 0.004  | 0.02 | 0.10   | 0.45 |
| 0805L075    | 0.08   | 0.09 | 2.00 | 2.20 | 0.05   | 0.06 | 1.20 | 1.50 | 0.03   | 0.05 | 0.75 | 1.25 | 0.01   | 0.20 | 0.006  | 0.02 | 0.15   | 0.45 |
| 0805L100    | 0.08   | 0.09 | 2.00 | 2.20 | 0.05   | 0.06 | 1.20 | 1.50 | 0.03   | 0.07 | 0.80 | 1.80 | 0.01   | 0.20 | 0.006  | 0.02 | 0.15   | 0.45 |

### Part Numbering System



### Packaging

| I <sub>hold</sub> (A) | I <sub>hold</sub> Code | Packaging Option | Quantity | Quantity & Packaging Codes |
|-----------------------|------------------------|------------------|----------|----------------------------|
| 0.10                  | 010                    | Tape and Reel    | 4000     | YR                         |
| 0.20                  | 020                    | Tape and Reel    | 4000     | YR                         |
| 0.35                  | 035                    | Tape and Reel    | 4000     | YR                         |
| 0.50                  | 050                    | Tape and Reel    | 3000     | WR                         |
| 0.75                  | 075                    | Tape and Reel    | 3000     | WR                         |
| 1.00                  | 100                    | Tape and Reel    | 3000     | WR                         |